



**Diode, Wechselrichter / Diode, Inverter**

**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	1200	V
Dauergleichstrom Continuous DC forward current		$I_F$	1400	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	2800	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	165 160	$\text{kA}^2\text{s}$ $\text{kA}^2\text{s}$
Spitzenverlustleistung Maximum power dissipation	$T_{vj} = 125^{\circ}\text{C}$	$P_{RQM}$	1400	kW

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 1400\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		1,90	2,30	V
	$I_F = 1400\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$		1,85	2,25	V
	$I_F = 1400\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		1,80	2,20	V
Rückstromspitze Peak reverse recovery current	$I_F = 1400\text{ A}, -di_F/dt = 8600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		780		A
	$V_R = 600\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$		1000		A
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		1050		A
Sperrverzögerungsladung Recovered charge	$I_F = 1400\text{ A}, -di_F/dt = 8600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		135		$\mu\text{C}$
	$V_R = 600\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$		235		$\mu\text{C}$
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		270		$\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 1400\text{ A}, -di_F/dt = 8600\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		70,0		mJ
	$V_R = 600\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$		110		mJ
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		130		mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode valid with IFX pre-applied thermal interface material	$R_{thJH}$			54,1	K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

**NTC-Widerstand / NTC-Thermistor**

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	$R_{25}$		5,00		$\text{k}\Omega$
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$	$\Delta R/R$	-5		5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	$P_{25}$			20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/50}$		3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/80}$		3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$	$B_{25/100}$		3433		K

Angaben gemäß gültiger Application Note.  
Specification according to the valid application note.

prepared by: SM	date of publication: 2016-09-06
approved by: RN	revision: V3.2



**Modul / Module**

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	4,0		kV
Material Modulgrundplatte Material of module baseplate			Cu		
Innere Isolation Internal isolation	Basisisolation (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		33,0 33,0		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		19,0 19,0		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L <sub>sCE</sub>		10	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T <sub>H</sub> = 25°C, pro Schalter / per switch	R <sub>CC'+EE'</sub>		0,20	mΩ
Lagertemperatur Storage temperature		T <sub>stg</sub>	-40		125 °C
Höchstzulässige Bodenplattenbetriebstemperatur Maximum baseplate operation temperature		T <sub>BPmax</sub>			125 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M5 - Montage gem. gültiger Applikationsschrift Screw M5 - Mounting according to valid application note	M	3,00		6,00 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M4 - Montage gem. gültiger Applikationsschrift Screw M4 - Mounting according to valid application note Schraube M8 - Montage gem. gültiger Applikationsschrift Screw M8 - Mounting according to valid application note	M	1,8 8,0	- -	2,1 10 Nm
Gewicht Weight		G		1200	g

Lagerung und Transport von Modulen mit TIM: siehe AN2012-07  
Storage and shipment of modules with TIM: see AN2012-07

prepared by: SM	date of publication: 2016-09-06
approved by: RN	revision: V3.2